

Title (en)
METHOD AND DEVICE FOR ENCAPSULATING MICROSTRUCTURES

Title (de)
VERFAHREN UND VORRICHTUNG ZUM EINKAPSELN VON MIKROSTRUKTUREN

Title (fr)
PROCEDE ET DISPOSITIF D'ENCAPSULATION DE MICROSTRUCTURES

Publication
EP 2321216 A2 20110518 (FR)

Application
EP 09740426 A 20090731

Priority
• FR 2009051544 W 20090731
• FR 0855357 A 20080801

Abstract (en)
[origin: WO2010012966A2] The present invention relates to a method for encapsulating structures (11) (typically MEMS structures) supported by a carrier substrate (12) (typically made of glass or silicon), which method comprises: application, on the carrier substrate (12), of at least one cover (7) supported by a mould (1, 2, 6), the mould comprising a catching layer (6), each cover (7) being in contact with the catching layer (6); then fastening of at least one cover (7) onto the carrier substrate (12); and then separation of the mould (1, 2, 6) from the at least one cover (7). The catching layer (6) comprises a fluoropolymer. Preferably, the mould (1, 2, 6) is separated from the at least one cover (7) by mechanical means, by pulling the mould (1, 2, 6) away from the at least one cover (7). Thus, the mould (1) can be reused, which considerably simplifies encapsulating operations carried out on an industrial scale.

IPC 8 full level
B81C 1/00 (2006.01); **B81B 7/02** (2006.01); **H05K 5/06** (2006.01)

CPC (source: EP US)
B81C 1/00269 (2013.01 - EP US); **B81C 2203/0127** (2013.01 - EP US); **Y10T 156/17** (2015.01 - EP US); **Y10T 428/23** (2015.01 - EP US)

Citation (search report)
See references of WO 2010012966A2

Designated contracting state (EPC)
AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO SE SI SK SM TR

Designated extension state (EPC)
AL BA RS

DOCDB simple family (publication)
WO 2010012966 A2 20100204; WO 2010012966 A3 20100325; EP 2321216 A2 20110518; FR 2934580 A1 20100205; FR 2934580 B1 20150116; JP 2011529798 A 20111215; US 2011165365 A1 20110707; US 8617413 B2 20131231

DOCDB simple family (application)
FR 2009051544 W 20090731; EP 09740426 A 20090731; FR 0855357 A 20080801; JP 2011520573 A 20090731; US 200913056796 A 20090731